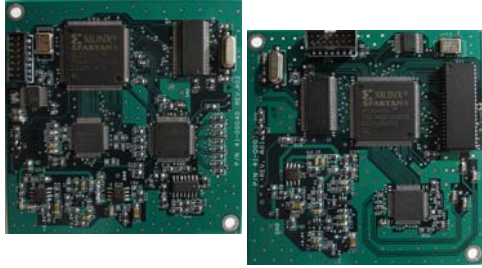


ExtremeUSB® 2.0 Core DL



LEX and REX Core Modules

2.0 Core DL - Product highlights

The ExtremeUSB 2.0 Core DL solution provides OEM customers with mechanical flexibility to integrate high-speed USB 2.0 extension into their own applications on their choice of transmission media.

ExtremeUSB 2.0 Core DL represents Icron's next generation of Core products which allow for integrated USB 2.0 extended range solutions.

- Extends the range of USB 2.0 connections up to 10 km
- ExtremeUSB 2.0 Core DL enables the digital connection LINK (PHY) between LEX (local extender unit) and REX (remote extender unit) to be chosen and implemented by the OEM.
- Reference designs using 2-pair UTP and 2-strand fiber-optic media are available from Icron. Alternative solutions that provide 600 Mb/s full-duplex bandwidth can also be employed.
- Icron's USB 2.0 Core DL will suit a wide variety of applications for the consumer electronics, medical, security, Pro A/V, environmental monitoring, KVM, financial, industrial control and flight simulation markets.

Design Features

- Supports USB 1.1 (low-speed, full-speed) and USB 2.0 (high-speed) devices at up to 480 Mb/s.
- True plug-and-play, no drivers required.
- Supports all major operating systems including Windows, Mac-OS, Sun and Linux.
- Can be mix & matched with other USB 2.0 Ranger LEX and REX modules
- Developer Kit includes application notes, design layouts and modules for rapid development.



Ordering Information

Name	Part Number	Description
ExtremeUSB 2.0 Core DL LEX	10-00090G	Local Extender (LEX) Module with digital link interface
ExtremeUSB 2.0 Core DL REX	10-00091G	Remote Extender (REX) Module with digital link interface
OEM Developer Kits		Includes LEX & REX motherboard, LEX & REX Modules (daughter boards), 2 power adapters and CD-ROM which include application notes and sample designs for UTP and Fiber transmission systems.
ExtremeUSB 2.0 Core Dev Kit	00-00198G	For North America
ExtremeUSB 2.0 Core Dev Kit	00-00199G	For Europe
ExtremeUSB 2.0 Core Dev Kit	00-00200G	For UK

Product Specification Highlights

LEX and REX Core DL Module dimensions
 Link Bandwidth required (UTP or Fiber PHY)
 Power Required - REX and LEX
 Temperature range

80mm x 80mm

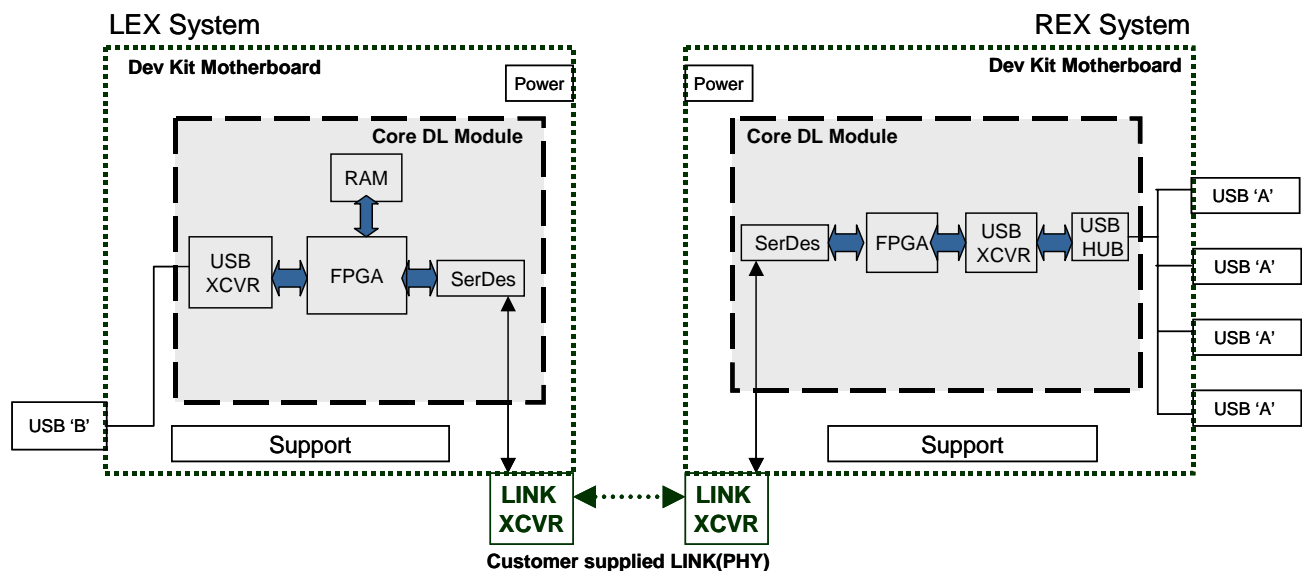
600 Mb/s

5V DC @ 700mA

0°C to 70°C - (for Core Modules only)

**industrial rating can be provided at additional cost*

Block Diagram



Specifications subject to change without notification